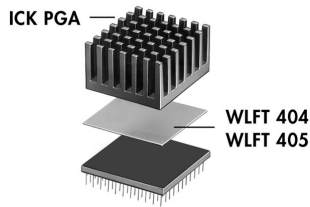


Data sheet Product ICK PGA 14 x 14 x 14



Heatsinks and active heatsinks for processors>Heatsinks for PGA
35 x 35 x 14 mm, for IC design PGA and others

Features

way of fixation:	<ul style="list-style-type: none"> • therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	35 mm
height:	14 mm
plate thickness:	2.5 mm
length:	35 mm
thermal resistance:	9.6 - 2 K/W
dissipation loss:	12.5 W
surface:	black anodised

Technical Drawing

